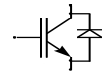


Technische Information / Technical Information

IGBT-Module
IGBT-Modules

FZ 1200 R 17 KF4C

eupec



Höchstzulässige Werte / Maximum rated values

Elektrische Eigenschaften / Electrical properties

Kollektor-Emitter-Sperrspannung collector-emitter voltage		V_{CES}	1700	V
Kollektor-Dauergleichstrom DC-collector current	$T_C = 80^\circ\text{C}$	$I_{C,nom.}$	1200	A
Periodischer Kollektor Spitzenstrom repetitive peak collector current	$t_p = 1\text{ ms}, T_C = 80^\circ\text{C}$	I_{CRM}	2400	A
Gesamt-Verlustleistung total power dissipation	$T_C = 25^\circ\text{C}$, Transistor	P_{tot}	7,8	kW
Gate-Emitter-Spitzenspannung gate-emitter peak voltage		V_{GES}	+/- 20V	V
Dauergleichstrom DC forward current		I_F	1200	A
Periodischer Spitzenstrom repetitive peak forw. current	$t_p = 1\text{ ms}$	I_{FRM}	2400	A
Grenzlastintegral der Diode I^2t - value, Diode	$V_R = 0\text{V}, t_p = 10\text{ms}, T_{vj} = 125^\circ\text{C}$	I^2t	380	kA^2s
Isolations-Prüfspannung insulation test voltage	RMS, $f = 50\text{ Hz}, t = 1\text{ min.}$	V_{ISOL}	3,4	kV

Charakteristische Werte / Characteristic values

Transistor / Transistor

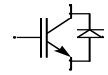
			min.	typ.	max.	
Kollektor-Emitter Sättigungsspannung collector-emitter saturation voltage	$I_C = 1200\text{A}, V_{GE} = 15\text{V}, T_{vj} = 25^\circ\text{C}$	$V_{CE\text{ sat}}$		3,5	3,9	V
	$I_C = 1200\text{A}, V_{GE} = 15\text{V}, T_{vj} = 125^\circ\text{C}$			4,6	5,0	V
Gate-Schwellenspannung gate threshold voltage	$I_C = 80\text{mA}, V_{CE} = V_{GE}, T_{vj} = 25^\circ\text{C}$	$V_{GE(th)}$	4,5	5,5	6,5	V
Gateladung gate charge	$V_{GE} = -15\text{V} \dots +15\text{V}$	Q_G		18		μC
Eingangskapazität input capacitance	$f = 1\text{MHz}, T_{vj} = 25^\circ\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$	C_{ies}		180		nF
Rückwirkungskapazität reverse transfer capacitance	$f = 1\text{MHz}, T_{vj} = 25^\circ\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$	C_{res}		4		nF
Kollektor-Emitter Reststrom collector-emitter cut-off current	$V_{CE} = 1700\text{V}, V_{GE} = 0\text{V}, T_{vj} = 25^\circ\text{C}$	I_{CES}		0,03	2,5	mA
	$V_{CE} = 1700\text{V}, V_{GE} = 0\text{V}, T_{vj} = 125^\circ\text{C}$			16	120	mA
Gate-Emitter Reststrom gate-emitter leakage current	$V_{CE} = 0\text{V}, V_{GE} = 20\text{V}, T_{vj} = 25^\circ\text{C}$	I_{GES}			400	nA

prepared by: Alfons Wiesenthal

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approved by:

revision: 3 (Ls geändert)



Charakteristische Werte / Characteristic values

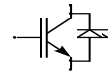
Transistor / Transistor

			min.	typ.	max.	
Einschaltverzögerungszeit (ind. Last) turn on delay time (inductive load)	$I_C = 1200A, V_{CE} = 900V$ $V_{GE} = \pm 15V, R_G = 1,8\Omega, T_{vj} = 25^\circ C$	$t_{d,on}$		0,3		μs
	$V_{GE} = \pm 15V, R_G = 1,8\Omega, T_{vj} = 125^\circ C$			0,5		μs
Anstiegszeit (induktive Last) rise time (inductive load)	$I_C = 1200A, V_{CE} = 900V$ $V_{GE} = \pm 15V, R_G = 1,8\Omega, T_{vj} = 25^\circ C$	t_r		0,25		μs
	$V_{GE} = \pm 15V, R_G = 1,8\Omega, T_{vj} = 125^\circ C$			0,25		μs
Abschaltverzögerungszeit (ind. Last) turn off delay time (inductive load)	$I_C = 1200A, V_{CE} = 900V$ $V_{GE} = \pm 15V, R_G = 1,8\Omega, T_{vj} = 25^\circ C$	$t_{d,off}$		1,1		μs
	$V_{GE} = \pm 15V, R_G = 1,8\Omega, T_{vj} = 125^\circ C$			1,3		μs
Fallzeit (induktive Last) fall time (inductive load)	$I_C = 1200A, V_{CE} = 900V$ $V_{GE} = \pm 15V, R_G = 1,8\Omega, T_{vj} = 25^\circ C$	t_f		0,12		μs
	$V_{GE} = \pm 15V, R_G = 1,8\Omega, T_{vj} = 125^\circ C$			0,13		μs
Einschaltverlustenergie pro Puls turn-on energy loss per pulse	$I_C = 1200A, V_{CE} = 900V, V_{GE} = 15V$ $R_G = 1,8\Omega, T_{vj} = 125^\circ C, L_S = 70nH$	E_{on}		490		mWs
Abschaltverlustenergie pro Puls turn-off energy loss per pulse	$I_C = 1200A, V_{CE} = 900V, V_{GE} = 15V$ $R_G = 1,8\Omega, T_{vj} = 125^\circ C, L_S = 70nH$	E_{off}		290		mWs
Kurzschlußverhalten SC Data	$t_p \leq 10\mu sec, V_{GE} \leq 15V$ $T_{vj} \leq 125^\circ C, V_{CC} = 1000V, V_{CEmax} = V_{CES} - L_{sCE} \cdot di/dt$	I_{SC}		10000		A
Modulinduktivität stray inductance module		L_{sCE}		12		nH
Modulleitungswiderstand, Anschlüsse - Chip module lead resistance, terminals - chip		R_{CC+EE}		0,08		m Ω

Charakteristische Werte / Characteristic values

Diode / Diode

			min.	typ.	max.	
Durchlaßspannung forward voltage	$I_F = 1200A, V_{GE} = 0V, T_{vj} = 25^\circ C$	V_F		2,1	2,5	V
	$I_F = 1200A, V_{GE} = 0V, T_{vj} = 125^\circ C$			2,1	2,5	V
Rückstromspitze peak reverse recovery current	$I_F = 1200A, -di_F/dt = 5000A/\mu sec$ $V_R = 900V, V_{GE} = -10V, T_{vj} = 25^\circ C$	I_{RM}		830		A
	$V_R = 900V, V_{GE} = -10V, T_{vj} = 125^\circ C$			900		A
Sperrverzögerungsladung recovered charge	$I_F = 1200A, -di_F/dt = 5000A/\mu sec$ $V_R = 900V, V_{GE} = -10V, T_{vj} = 25^\circ C$	Q_r		220		μAs
	$V_R = 900V, V_{GE} = -10V, T_{vj} = 125^\circ C$			400		μAs
Abschaltenergie pro Puls reverse recovery energy	$I_F = 1200A, -di_F/dt = 5000A/\mu sec$ $V_R = 900V, V_{GE} = -10V, T_{vj} = 25^\circ C$	E_{rec}		100		mWs
	$V_R = 900V, V_{GE} = -10V, T_{vj} = 125^\circ C$			190		mWs



Thermische Eigenschaften / Thermal properties

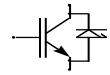
			min.	typ.	max.	
Innerer Wärmewiderstand thermal resistance, junction to case	Transistor / transistor, DC	R_{thJC}			0,016	K/W
	Diode/Diode, DC				0,04	K/W
Übergangs-Wärmewiderstand thermal resistance, case to heatsink	pro Modul / per module $\lambda_{Paste} = 1 \text{ W/m}^2\text{K}$ / $\lambda_{grease} = 1 \text{ W/m}^2\text{K}$	R_{thCK}		0,008		K/W
Höchstzulässige Sperrschichttemperatur maximum junction temperature		T_{vj}			150	°C
Betriebstemperatur operation temperature		T_{op}	-40		125	°C
Lagertemperatur storage temperature		T_{stg}	-40		125	°C

Mechanische Eigenschaften / Mechanical properties

Gehäuse, siehe Anlage case, see appendix					
Innere Isolation internal insulation				Al_2O_3	
Kriechstrecke creepage distance				17	mm
Luftstrecke clearance				10	mm
CTI comperative tracking index				275	
Anzugsdrehmoment f. mech. Befestigung mounting torque		M1		5	Nm
Anzugsdrehmoment f. elektr. Anschlüsse terminal connection torque	terminals M4	M2		2	Nm
	terminals M8			8 - 10	Nm
Gewicht weight		G		1500	g

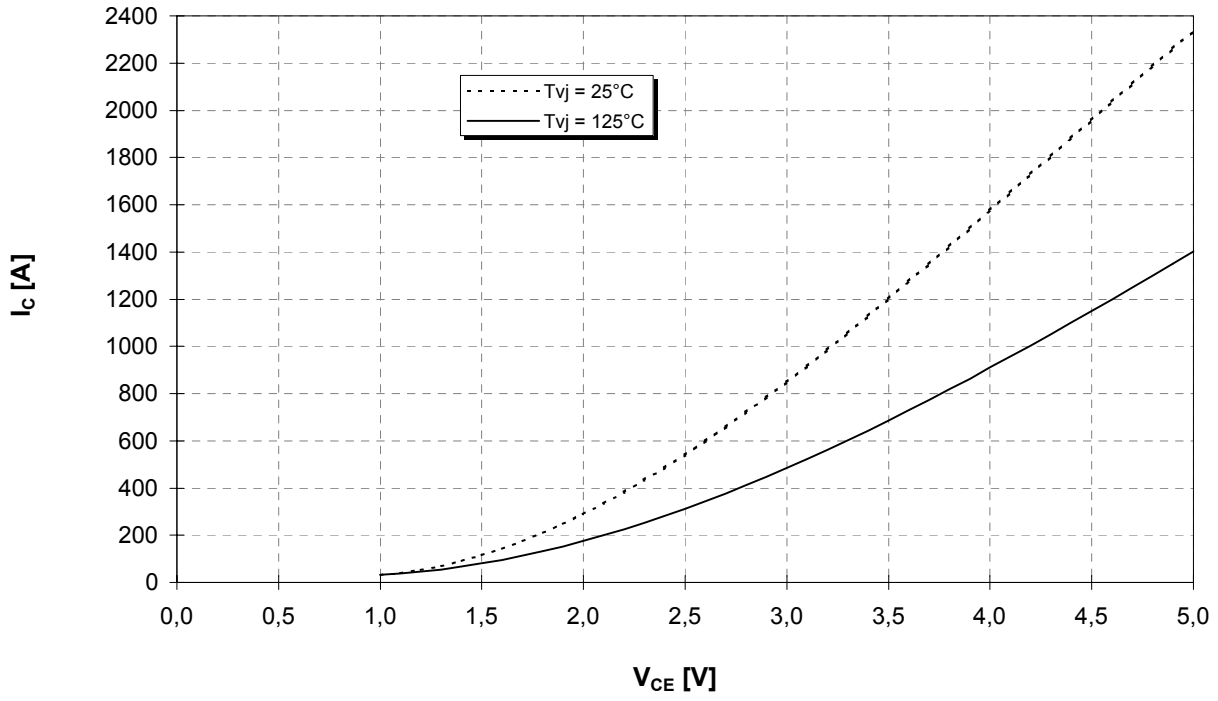
Mit dieser technischen Information werden Halbleiterbauelemente spezifiziert, jedoch keine Eigenschaften zugesichert. Sie gilt in Verbindung mit den zugehörigen Technischen Erläuterungen.

This technical information specifies semiconductor devices but promises no characteristics. It is valid in combination with the belonging technical notes.



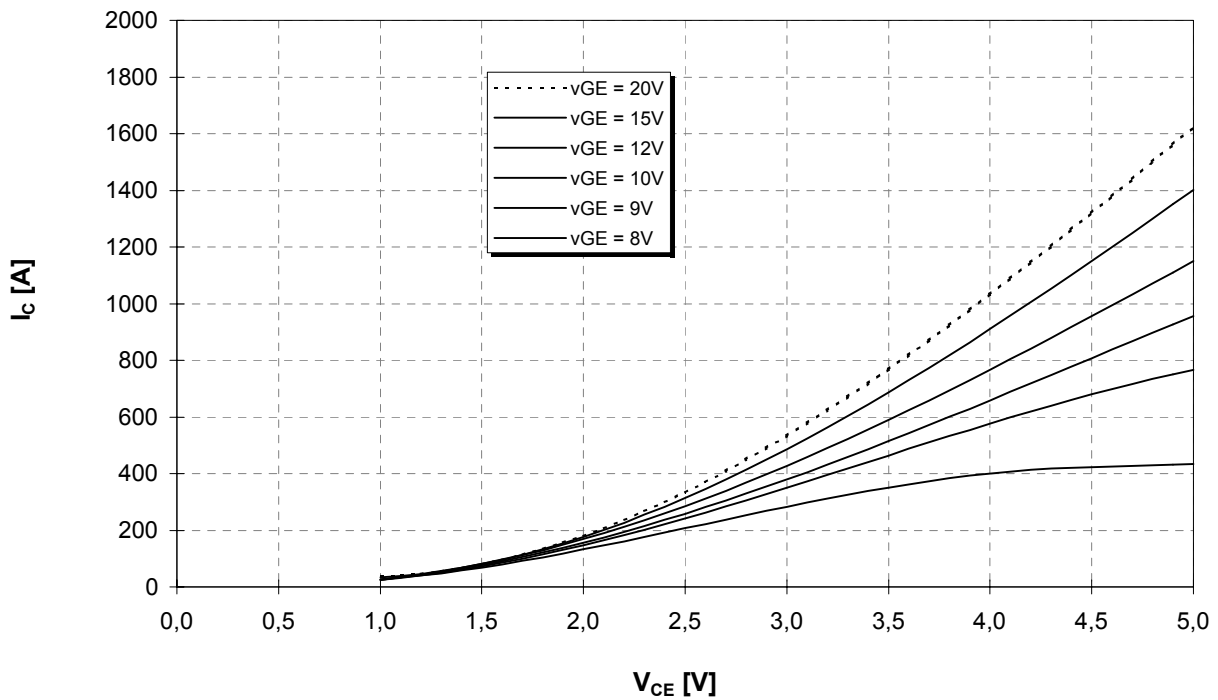
Ausgangskennlinie (typisch)
Output characteristic (typical)

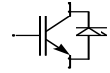
$I_C = f(V_{CE})$
 $V_{GE} = 15V$



Ausgangskennlinienfeld (typisch)
Output characteristic (typical)

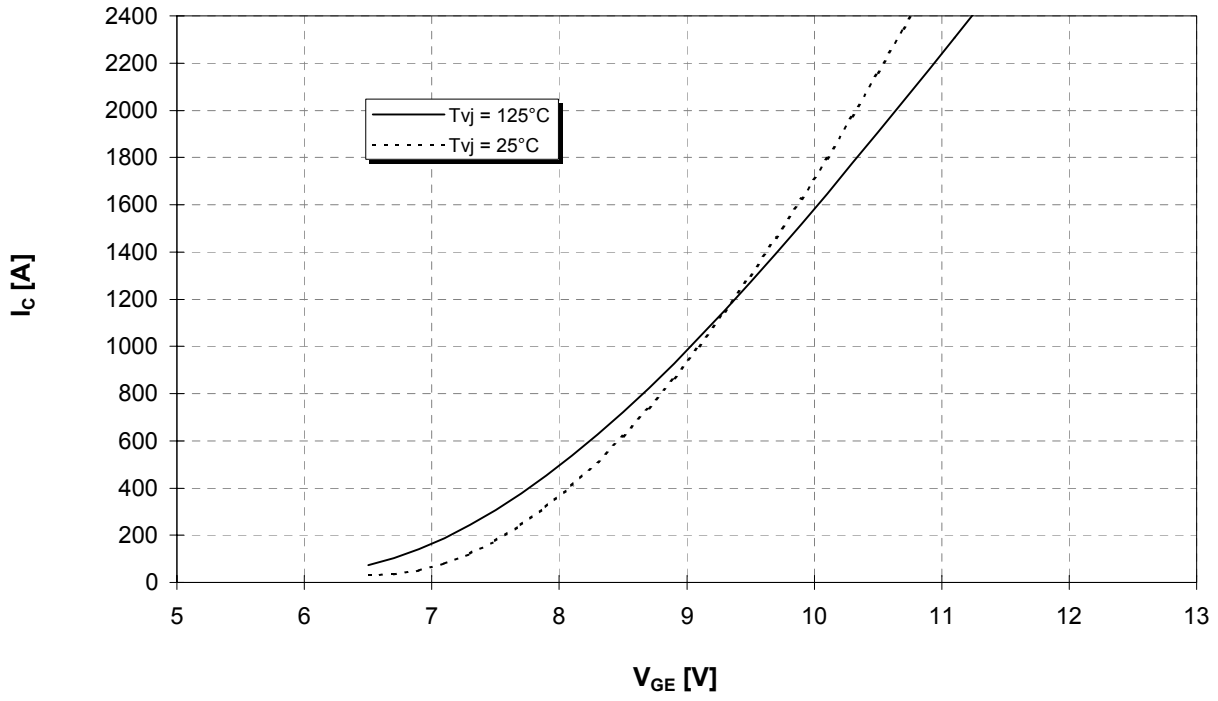
$I_C = f(V_{CE})$
 $T_{vj} = 125^\circ C$





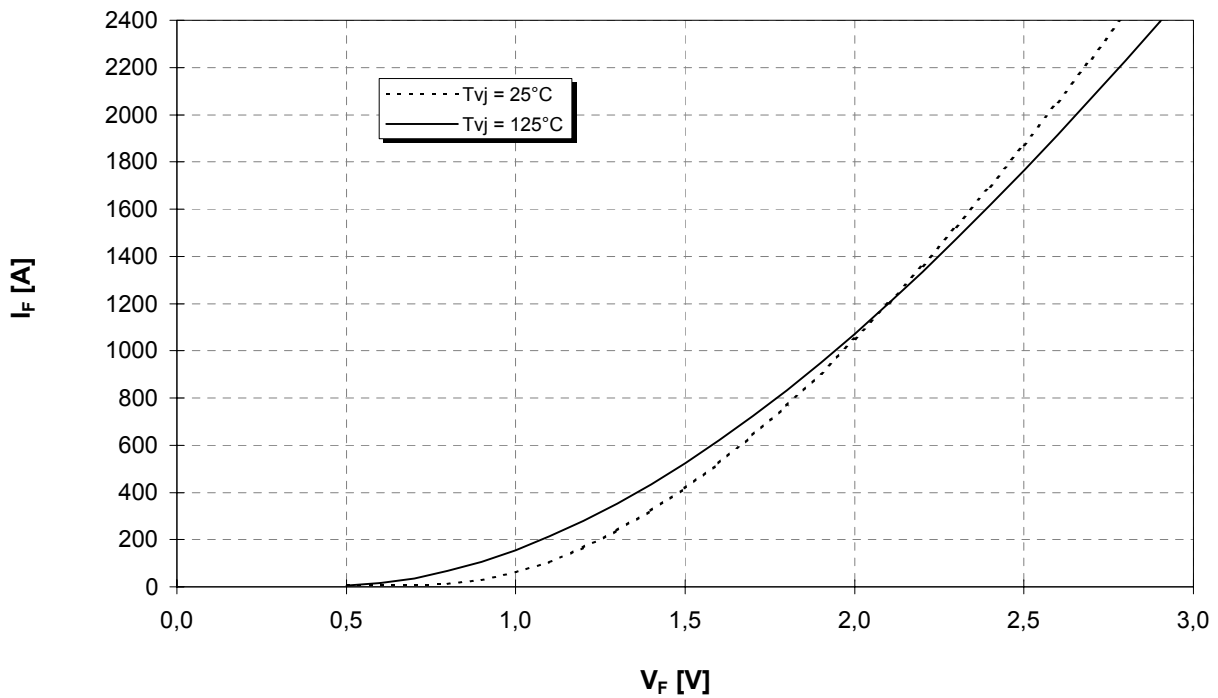
Übertragungscharakteristik (typisch)
Transfer characteristic (typical)

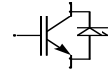
$I_C = f(V_{GE})$
 $V_{CE} = 20V$



Durchlaßkennlinie der Inversdiode (typisch)
Forward characteristic of inverse diode (typical)

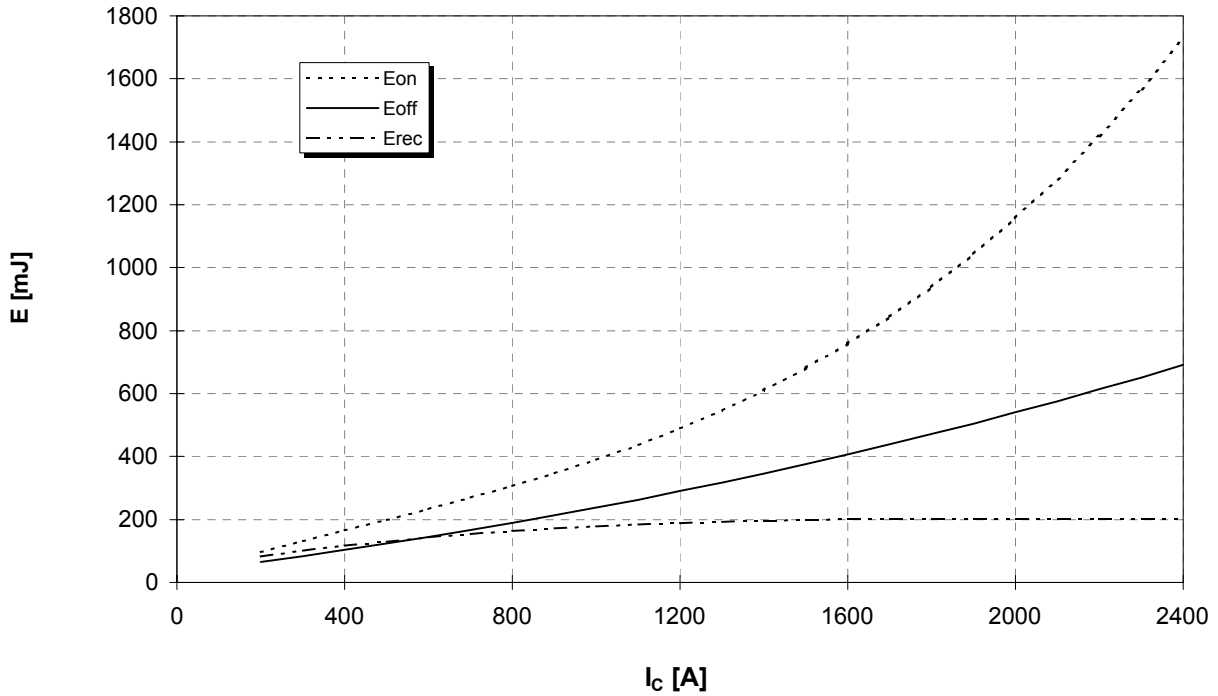
$I_F = f(V_F)$





Schaltverluste (typisch) $E_{on} = f(I_C), E_{off} = f(I_C), E_{rec} = f(I_C)$

Switching losses (typical) $R_{gon} = R_{goff} = 1,8 \Omega, V_{CE} = 900V, T_J = 125^\circ C, V_{GE} = \pm 15V$

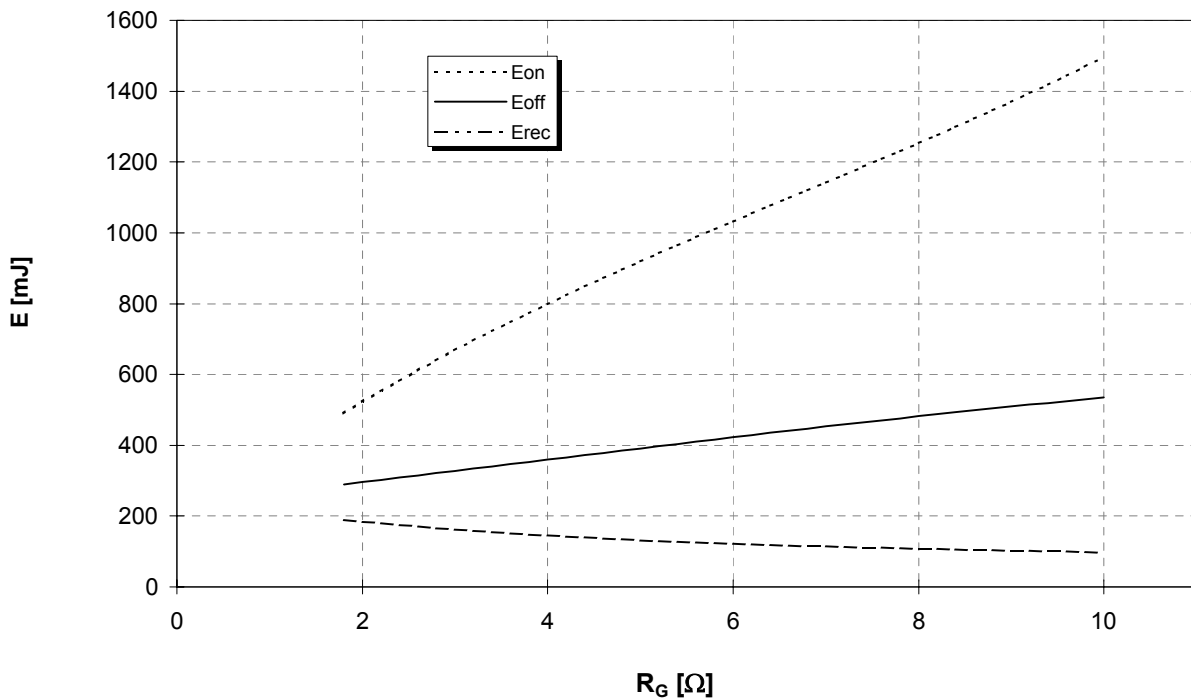


Schaltverluste (typisch)

$E_{on} = f(R_G), E_{off} = f(R_G), E_{rec} = f(R_G)$

Switching losses (typical)

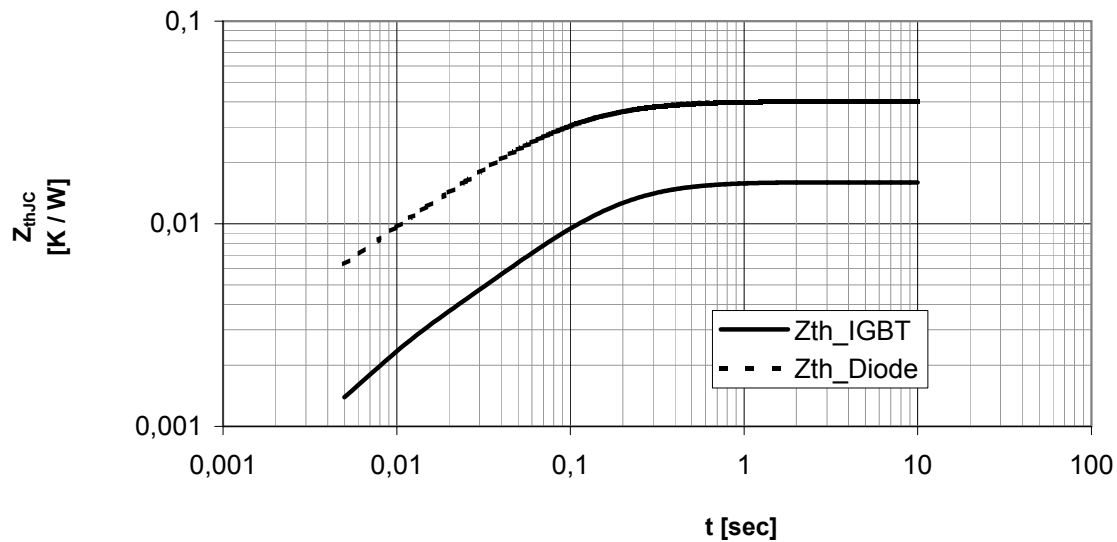
$I_C = 1200A, V_{CE} = 900V, T_J = 125^\circ C, V_{GE} = \pm 15V$





Transienter Wärmewiderstand
Transient thermal impedance

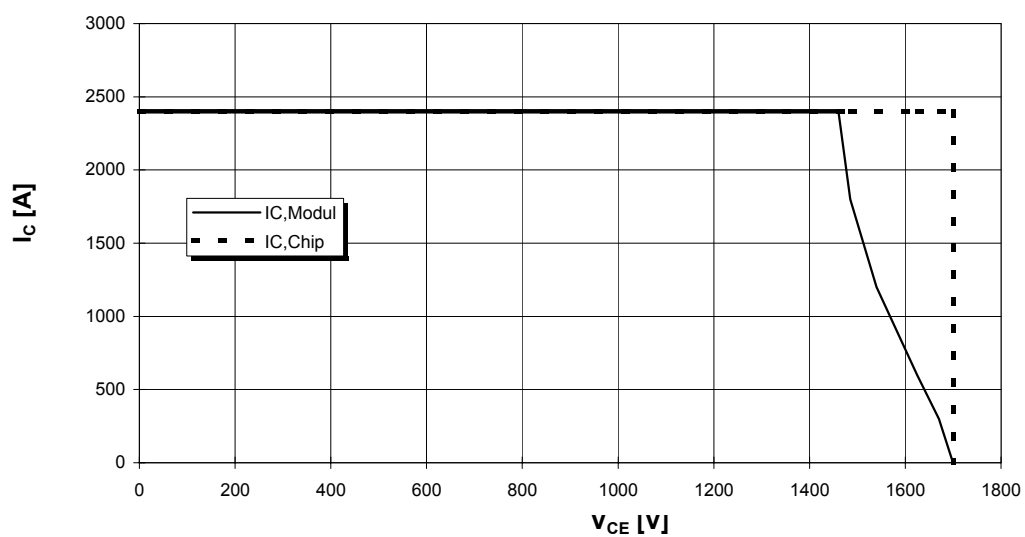
$Z_{thJC} = f(t)$

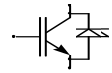


i	1	2	3	4
r_i [K/kW] : IGBT	1,55	5,79	6,28	2,38
τ_i [sec] : IGBT	0,007	0,082	0,135	0,38
r_i [K/kW] : Diode	4,07	13,84	17,56	4,53
τ_i [sec] : Diode	0,003	0,032	0,089	0,316

Sicherer Arbeitsbereich (RBSOA)
Reverse bias safe operation area (RBSOA)

$R_g = 1,8 \text{ Ohm}, T_{vj} = 125^\circ\text{C}$





Äußere Abmessungen / external dimensions

